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(54) **DUAL OPTICAL ELECTRICAL
CONVERSION MODULE**

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(71) Applicant: **FINISAR CORPORATION**,
Sunnyvale, CA (US)
(72) Inventor: **Giuliano Coli**, Sunnyvale, CA (US)
(73) Assignee: **FINISAR CORPORATION**,
Sunnyvale, CA (US)
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Primary Examiner — Ken Vanderpuye

Assistant Examiner — Abbas H Alagheband

(74) *Attorney, Agent, or Firm* — Maschoff Brennan

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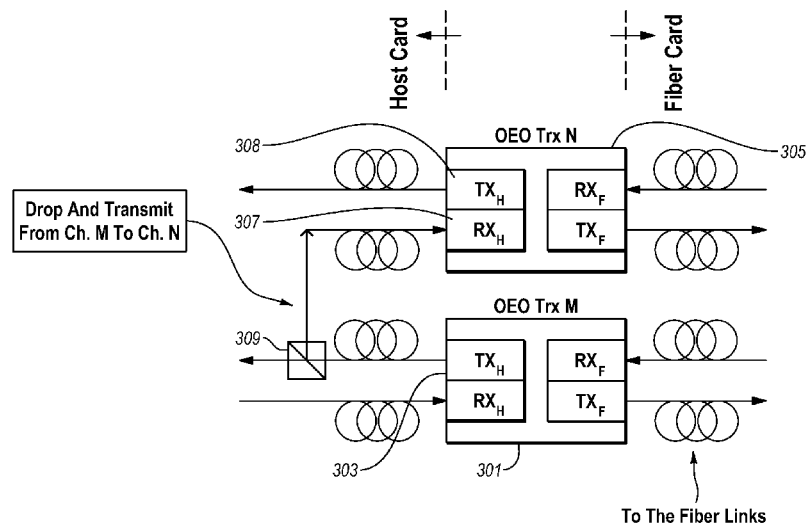
CPC ... H04B 10/038; H04B 10/0731; H04B 10/40
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ABSTRACT

In an embodiment, a dual optical-electrical conversion (DOEC) module is described that includes an optical host interface, an optical network interface, and an integrated circuit. The optical host interface includes an optical transmitter and an optical receiver. The optical network interface includes an optical transmitter and an optical receiver. The integrated circuit conditions electrical signals communicated between the optical host interface and optical network interface. Optical signals received at and transmitted by the optical host interface may have different parameter requirements than optical signals received at and transmitted by the optical network interface, such as different wavelength parameters and/or fiber link length parameters.

18 Claims, 5 Drawing Sheets



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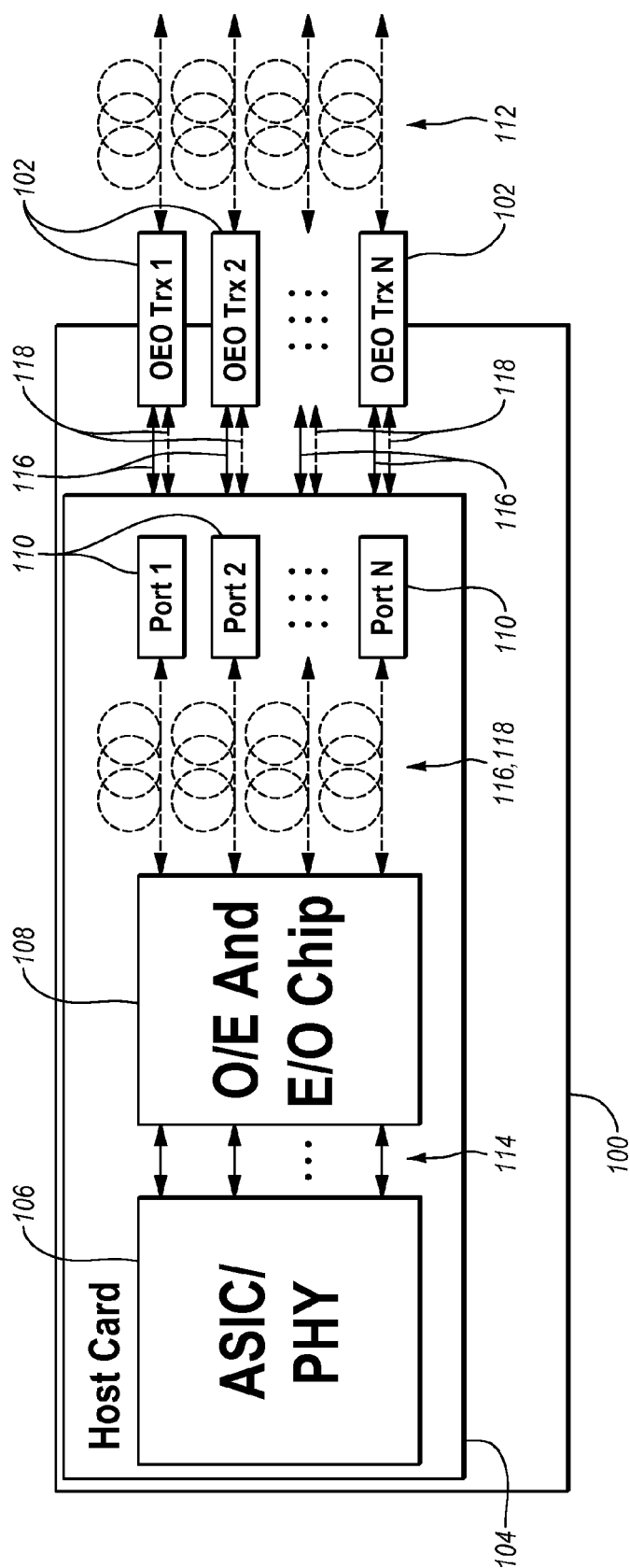


Fig. 1

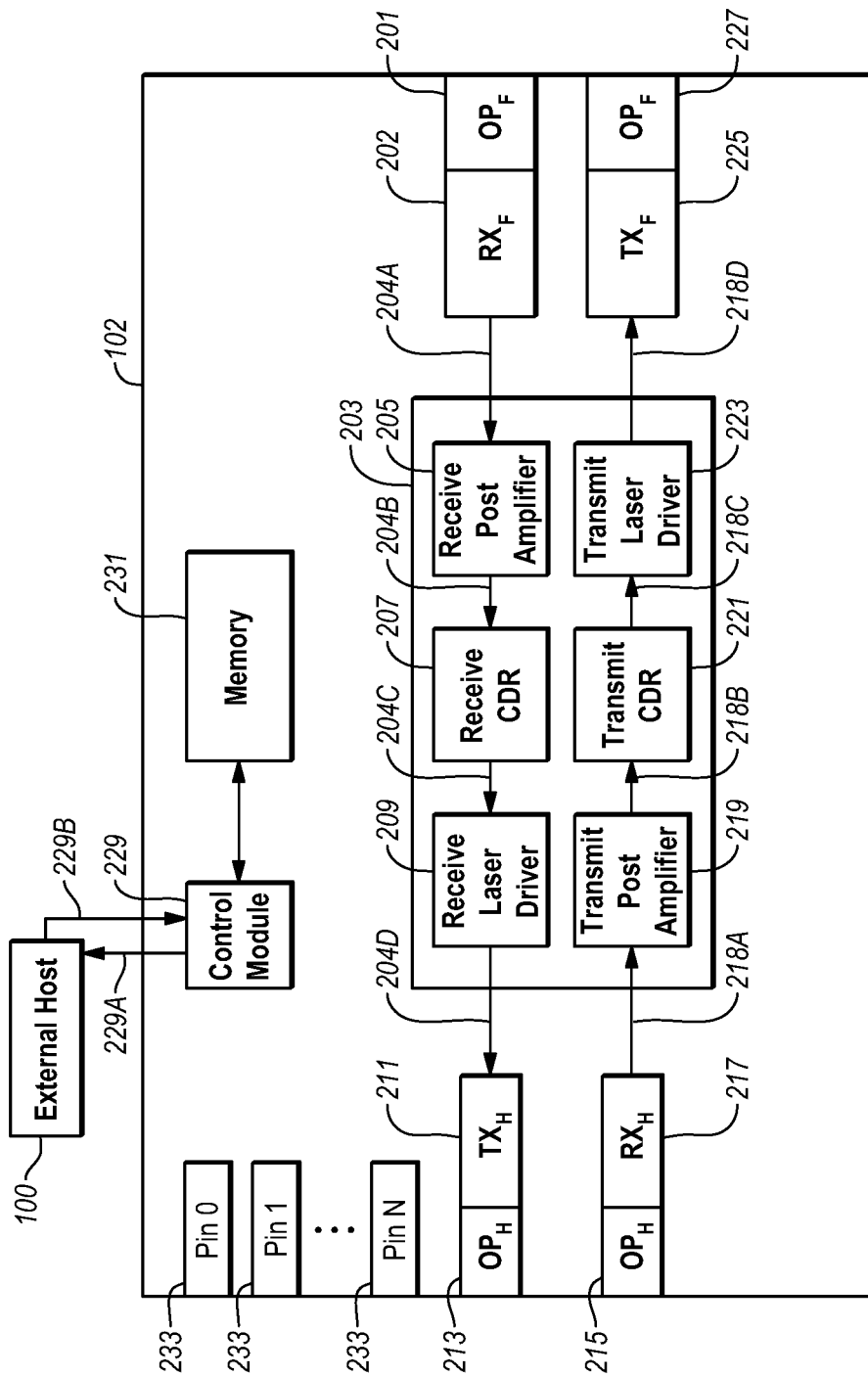


Fig. 2

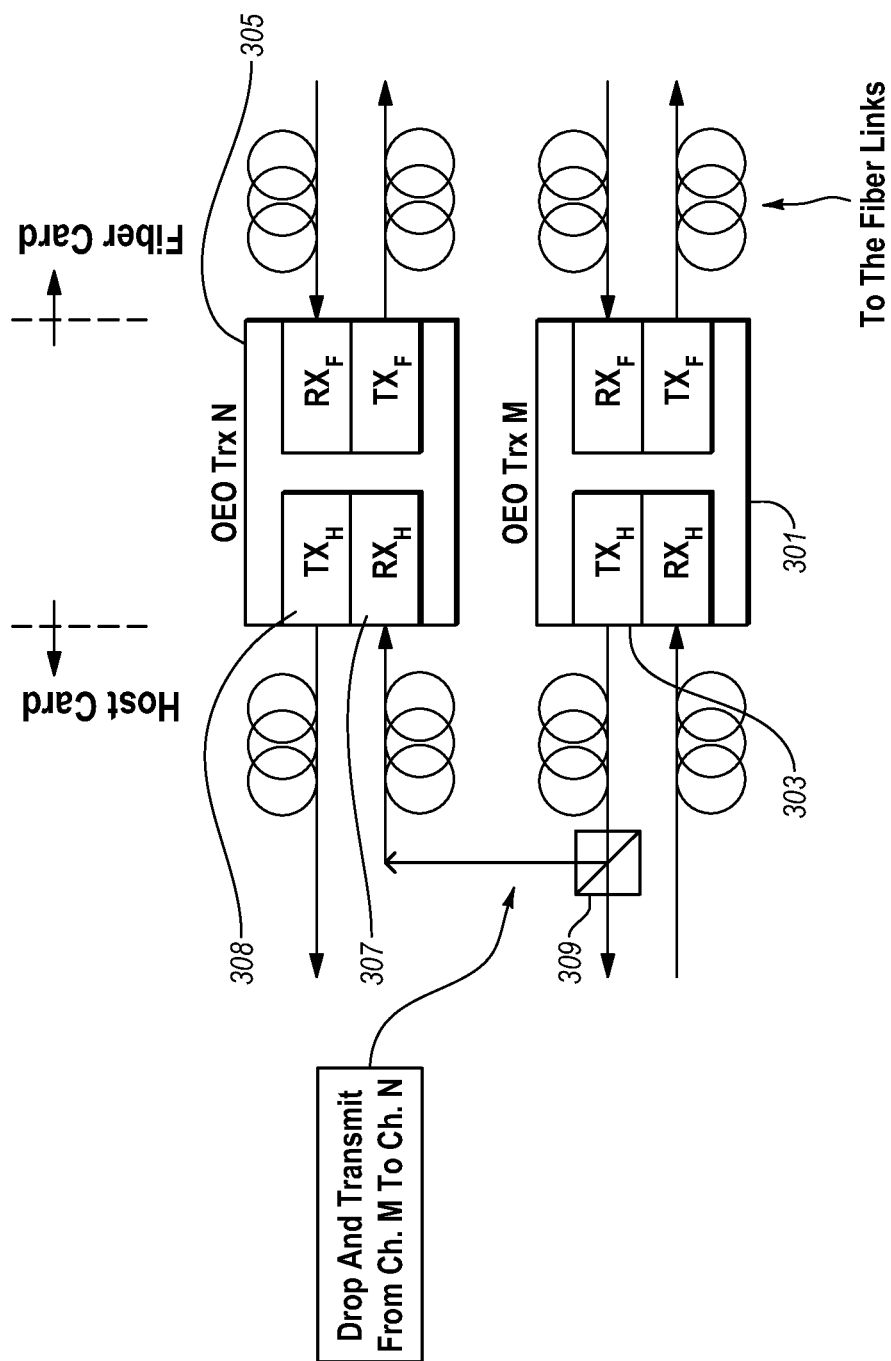
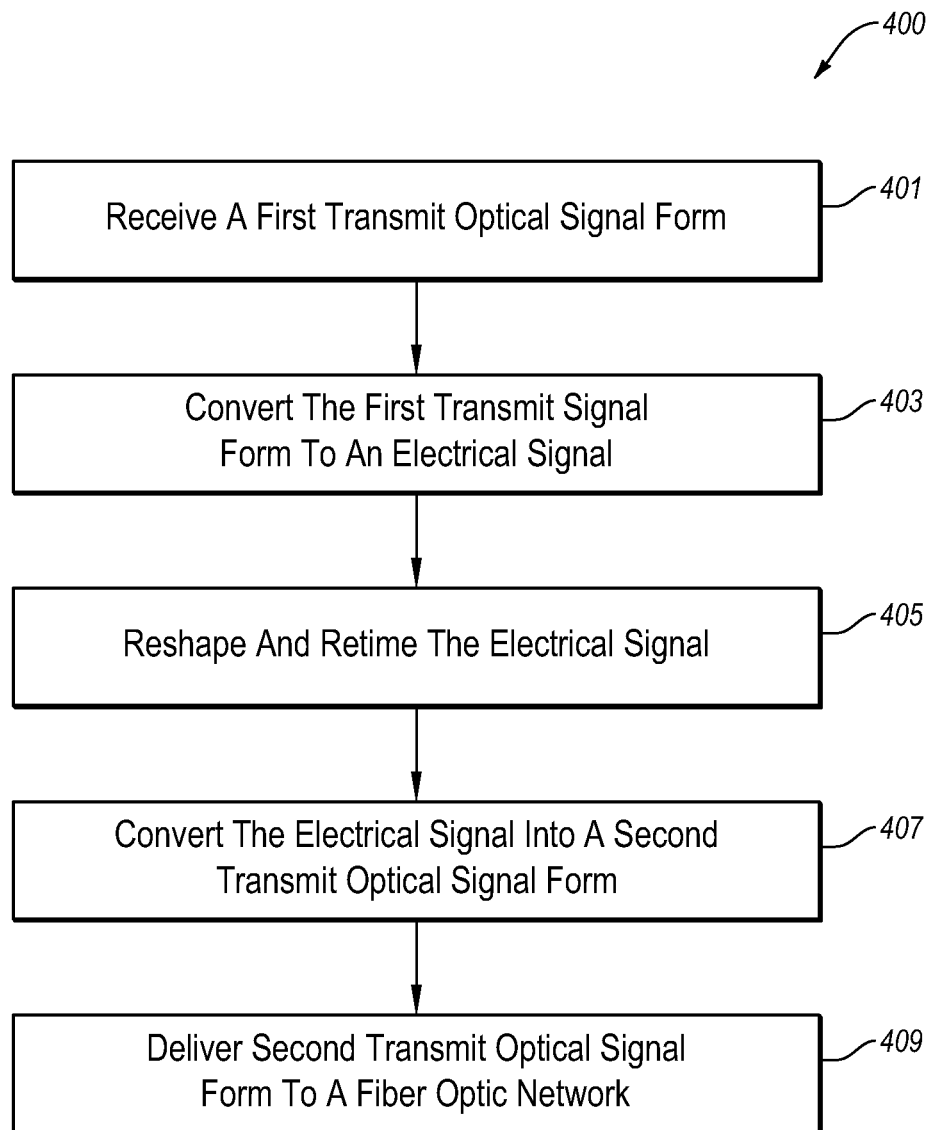
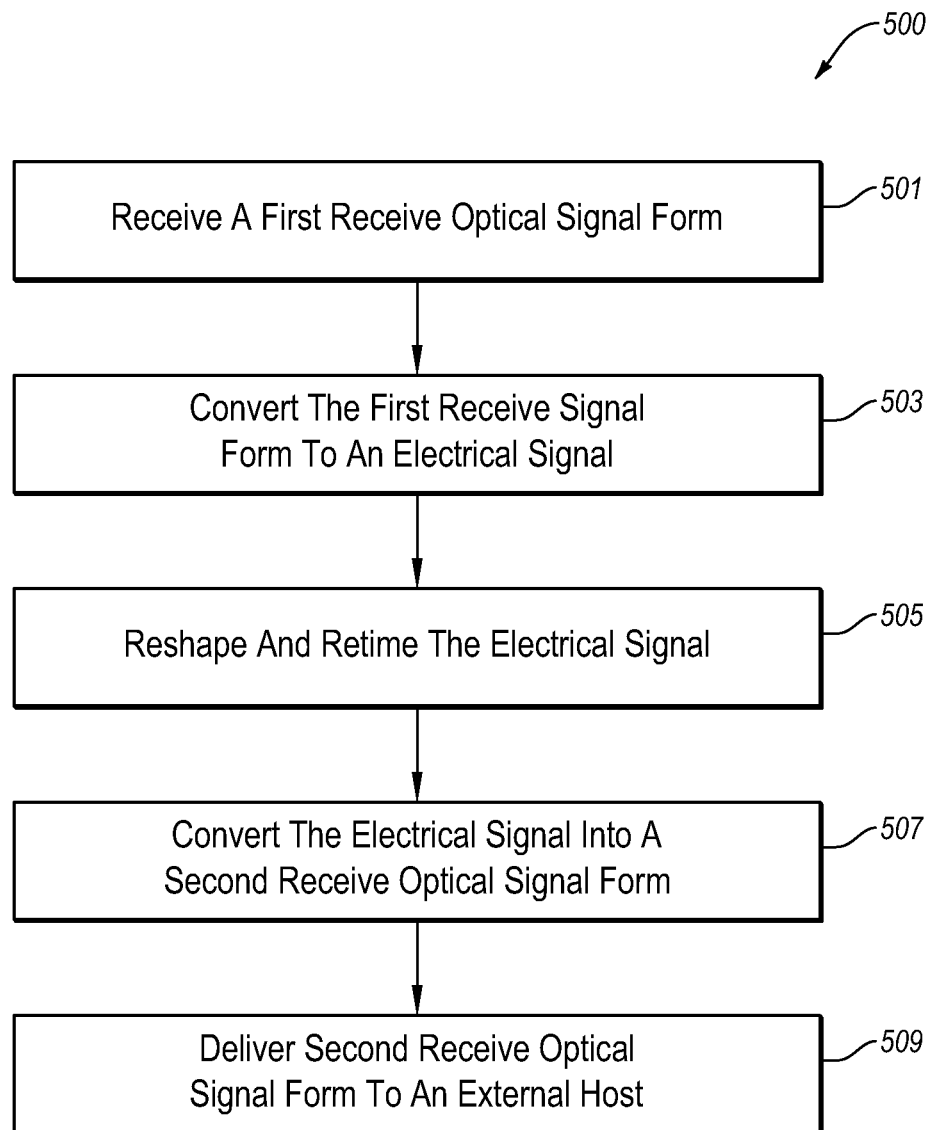


Fig. 3

**Fig. 4**

**Fig. 5**

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DUAL OPTICAL ELECTRICAL CONVERSION MODULE

FIELD

The embodiments discussed herein are related to dual optical-electrical conversion modules that can convert an electrical signal to an optical signal conditioned to communicate with fibers and ports of various wavelength and link length specifications.

BACKGROUND

Computing and networking technology have transformed our world. As the amount of information communicated over networks has increased, high speed transmission has become ever more critical. Many high speed transmission networks rely on optical communication devices for facilitating transmission over long distances through optical fiber links. Optical networks are thus found in a wide variety of high speed applications ranging from data center Local Area Networks (LAN) to metro and long haul optical fiber links for Internet, Voice and Video communications.

Although information data is transported over optical fibers, processing the data is still performed mainly on the host cards by Application Specific Integrated Circuits or Physical layer chips (ASIC/PHY chips). This still requires transmission through electrical traces, with losses that increase dramatically with increasing bit rate and traces' lengths. One solution to this problem is to use an electro-optical (e/o) conversion chip, also referred to as an e/o chip, on the host card, between the ASIC/PHY and the optical ports facing the optical links, but this solution limits the communication to specific link lengths and wavelengths.

The subject matter claimed herein is not limited to embodiments that solve any disadvantages or that operate only in environments such as those described above. Rather, this background is only provided to illustrate one exemplary technology area where some embodiments described herein may be practiced.

BRIEF SUMMARY OF SOME EXAMPLE EMBODIMENTS

Embodiments described herein generally relate to a dual optical-electrical conversion (DOEC) module.

In an example embodiment, a DOEC module includes an optical host interface, an optical network interface, and an integrated circuit. The optical host interface includes a transmitter and a receiver. The optical network interface includes a transmitter and a receiver. The integrated circuit is configured to condition electrical signals communicated between the optical host and optical network interfaces.

In another example embodiment, a method for transforming an optical signal is described. The method includes receiving a first optical signal. The method also includes converting the first optical signal to an electrical signal. The method also includes converting the reshaped and retimed electrical signal into a second optical signal. The second optical signal can be conditioned through this process to be transmittable over an optical network of varying parameters, such as of varying link lengths and wavelengths.

In yet another example embodiment, a system for transforming optical data signals to be adaptable to differing parameters between a host and a network is described. The system include an ASIC/PHY chip, an electro/optical conversion chip (e/o chip) coupled to the ASIC/PHY chip, multiple

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ports optically coupled to the e/o chip, and multiple DOEC modules each optically coupled to a corresponding one of the optical ports on a host side and to a network on a network side of the corresponding module. The e/o chip is configured to convert electrical data signals from the ASIC/PHY chip to optical data signals in a first form emitted to the DOEC modules coupled to the ports. Each of the DOEC modules is configured to convert optical data signals in the first form received from the e/o chip to optical data signals in a second form emitted onto the network. Each of the DOEC modules is further configured to convert optical data signals in a third form received from the network to optical data signals in a fourth form emitted to the e/o chip. The e/o chip is further configured to convert optical data signals in the fourth form received from the DOEC modules to electrical data signals emitted to the ASIC/PHY chip.

Utilizing a DOEC module, the system can allow optical networks of differing link lengths and wavelengths to deliver receive optical signals to a host. Likewise, the DOEC module can allow a host network to deliver transmit signals to optical networks of differing link lengths and wavelengths. In these and other embodiments, the DOEC module implements optical communication between the host and the port interfacing the link at data speeds that are higher than otherwise possible with electrical traces, and without limiting the ports on the host to single wavelength and link length applications.

Additional features and advantages of the invention will be set forth in the description which follows, and in part will be obvious from the description, or may be learned by the practice of the invention. The features and advantages of the invention may be realized and obtained by means of the instruments and combinations particularly pointed out in the appended claims. These and other features of the present invention will become more fully apparent from the following description and appended claims, or may be learned by the practice of the invention as set forth hereinafter.

BRIEF DESCRIPTION OF THE DRAWINGS

To further clarify the above and other advantages and features of the present invention, a more particular description of the invention will be rendered by reference to specific embodiments thereof which are illustrated in the appended drawings. Understanding that these drawings depict only several embodiments in accordance with the disclosure and are, therefore, not to be considered limiting of its scope, the disclosure will be described with additional specificity and detail through use of the accompanying drawings, in which:

FIG. 1 schematically illustrates an example operating environment including one or more DOEC modules communicatively coupled to a host ASIC/PHY card;

FIG. 2 schematically illustrates an example embodiment of a DOEC module that may be implemented in the operating environment of FIG. 1;

FIG. 3 schematically illustrates an example of how multiple DOEC modules may cooperate to perform drop and transmit functions;

FIG. 4 is a flowchart of an example method for converting a transmit optical signal; and

FIG. 5 is a flowchart of an example method for converting a receive optical signal;

all arranged in accordance with at least one of the embodiments described herein, and which arrangement may be modified in accordance with the disclosure provided herein by one of ordinary skill in the art

DETAILED DESCRIPTION OF SOME EXAMPLE EMBODIMENTS

Example embodiments generally relate to techniques for enabling an optical host interface to transmit signals over any one of multiple fiber optic link lengths and/or using any one of multiple different wavelengths.

As mentioned above, some host ASIC/PHY cards may include an e/o chip. In these and other embodiments, an e/o chip on a host card typically only supports fiber-optic links of the same length and wavelength over all ports of the host line card. Accordingly, some example embodiments relate to a DOEC module (see **102** in FIG. 1), such as a transceiver or transponder that communicates optically, rather than electrically, with a host card, such as a host card that has an e/o chip.

FIG. 1 illustrates an example operating environment including one or more DOEC modules **102** communicatively coupled to an external host **100** including a host card **104**. As illustrated, the host card **104** includes an ASIC/PHY chip **106**, an e/o chip **108**, and one or more ports **110**. Each of the DOEC modules **102** may include one or more components as discussed below with respect to FIG. 2.

In general, the host card **104** may be configured to transmit data to and receive data from a network over fiber links **112**, each of which may include one or more optical fibers. Alternatively, in systems that implement wavelength division multiplexing (WDM), each of the fiber links **112** may include a distinct wavelength channel on the same optical fiber. The data communicated over the fiber links **112** may be variously embodied as high bandwidth electrical data signals **114** between the ASIC/PHY chip **106** and the e/o chip **108**, high bandwidth optical data signals **116**, **118** between the e/o chip **108** and the DOEC modules **102**, and high bandwidth optical data signals (not shown) communicated on the fiber links **112**. The high bandwidth optical data signals **116**, **118** include receive optical signals **116** and transmit optical signals **118**.

In a transmit direction (e.g., from the ASIC/PHY chip **106** to the network), the ASIC/PHY chip **106** is configured to generate electrical transmit signals which are provided to the e/o chip **108**. The electrical transmit signals generated by the ASIC/PHY chip **106** are not separately labeled but are included in the high bandwidth electrical data signals **114**.

The e/o chip **108** is configured to convert the electrical transmit signals received from the ASIC/PHY chip **106** to transmit optical signals **118** included in the high bandwidth optical data signals **116**, **118**. Optionally, each of the transmit optical signals **118** may be communicated via respective ports **110** and over an optical fiber or other waveguide (not shown) to respective DOEC modules **102**.

The ports **110** may include a mechanical interface through which the transmit optical signals generated by the e/o chip **108** may be transmitted to the DOEC modules **102**, as well as electrical connections (not shown) to supply power to the DOEC modules **102**.

In general, each of the DOEC modules **102** is configured to receive and optionally condition a respective one of the transmit optical signals generated by the e/o chip **108** for transmission over a respective one of the fiber links **112**. Specifically, whereas each of the fiber links **112** may have a different length, each DOEC module **102** may convert the received transmit optical signal to an electrical signal, optionally condition the electrical signal as appropriate for a length of the respective fiber link **112**, and emit an optical signal representative of the electrical signal at a desired wavelength.

In a receive direction (e.g., from the network to the ASIC/PHY chip **106**), the DOEC modules **102** are each configured to receive and optionally condition an optical signal from a

respective one of the fiber links **112** for reception by the host card **104**. Specifically, each DOEC module **102** may convert the optical signal received from the respective fiber link **112** to an electrical signal, optionally condition the electrical signal as appropriate for transmission to the e/o chip **108**, and emit a receive optical signal **116** representative of the electrical signal through the corresponding port **110** to the e/o chip **108**. As mentioned previously, the receive optical signals **116** are included in the high bandwidth optical data signals **116**, **118**. Optionally, each of the receive optical signals **116** may be communicated over an optical fiber or other waveguide (not shown) to respective ports **110**.

The e/o chip **108** is configured to convert the receive optical signals received from the DOEC modules **102** to electrical receive signals. Accordingly, the e/o chip **108** provides an opto-electrical (o/e) conversion and could alternatively be referred to as an "o/e chip," an "o/e and e/o chip," or other similar term. For simplicity, the chip **108** will generally be referred to herein as an "e/o chip." The electrical receive signals generated by the e/o chip **108** are not separately labeled but are included in the high bandwidth electrical data signals **114**.

The ASIC/PHY chip **106** receives the electrical receive signals from the e/o chip **108**.

Optionally, a low-speed electrical interface (not shown) may be provided between the host card **104** and the DOEC modules **102** over which low-speed data signals (such as alarms/warnings, controls and digital diagnostic monitoring, and the like) may be communicated electrically between the host card **104** and the DOEC modules **102**. Alternately or additionally, the low-speed data may be communicated optically between the DOEC modules **102** and the host card **104**.

FIG. 2 illustrates an example embodiment of one of the DOEC modules **102** that may be implemented in the operating environment of FIG. 1. Each of the DOEC modules **102** of FIG. 1 may have the same configuration as the DOEC module **102** of FIG. 2, for instance. While the DOEC module **102** will be described in some detail, the DOEC module **102** is described by way of illustration only, and not by way of restricting the scope of the invention. The principles of the example embodiments described herein are suitable for any bit rate, i.e. 1 gigabit per second (G), 2G, 4G, 8G, 10G, 16G, 28G, 40G, 100G, and higher or other bandwidth fiber optic links. Furthermore, the principles described herein may be implemented in DOEC modules of any form factor such as XFP, SFP, SFF, SFP+, QSFP+, CFP, and active optical cables, without restriction. It will be appreciated, however, that the DOEC modules **102** need not comply with standardized form factor requirements and may have any size or configuration necessary according to a particular design.

The DOEC module **102** is configured to receive an optical signal from a fiber included in a corresponding fiber link **112** (FIG. 1) through a fiber-side optical port **201** at a fiber-side receiver **202**. The fiber-side receiver **202** acts as an opto-electric transducer by transforming the optical signal into an electrical signal **204A**. The electrical signal **204A** may then be provided to one or more optional integrated circuits **203** including one or more of a receive post amplifier **205**, a receive clock and data recovery **207** (CDR), and a receive laser driver **209**. Alternately or additionally, the integrated circuit **203** may include a transmit post amplifier **219**, a transmit CDR **221**, and a transmit laser driver **223**. The integrated circuit **203** including the receive post amplifier **205**, the receive CDR **207**, the receive laser driver **209**, the transmit post amplifier **219**, the transmit CDR **221** and the transmit laser driver **223** may be integrated in the same chip, may be implemented in separate chips, or any combination thereof.

The receive post amplifier **205** amplifies the electrical signal **204A** to generate an amplified signal **204B** and provides the amplified signal **204B** to the receive CDR **207**. The receive CDR **207** may, in some embodiments, reshape and retimed the amplified signal **204B** to generate a reshaped and retimed signal **204C**. The reshaped and retimed signal **204C** may be provided to a receive laser driver **209**. The receive laser driver **209** receives the reshaped and retimed signal **204C** and drives a host-side transmitter **211** with a drive signal **204D** that causes the host-side transmitter **211** to emit an optical signal, e.g., included in the high bandwidth optical data signals **116**, **118** of FIG. 1, representative of the information in the reshaped and retimed signal **204C**. The host-side transmitter **211** acts as an electro-optic transducer by transforming the drive signal **204D** into an optical signal. The optical signal emitted by the host-side transmitter **211** may then be transmitted through a host-side port **213** and provided to the host card **104** (FIG. 1) of the external host **100**. In some embodiments, the reshaping performed by the receive CDR **207** and the configuration of the host-side transmitter **211** conditions and/or configures the optical signal emitted by the host-side transmitter **211** for the specific conditions (e.g., link length, wavelength channel) of the link between the host-side transmitter **211** and the host card **104**. Accordingly, the DOEC module **102** may enable an optical signal to be suitable for any external host **100** with any given wavelength and link length parameters.

The DOEC module **102** is also configured to receive an optical signal, e.g., included in the high bandwidth optical data signals **116**, **118** of FIG. 1, from the e/o chip **108** through a host-side optical port **215** at a host-side receiver **217**. The host-side receiver **217** acts as an opto-electric transducer by transforming the optical signal into an electrical signal **218A**. The electrical signal **218A** may then be provided to a transmit post amplifier **219** included in the integrated circuit **203**, which additionally includes a transmit CDR **221** and a transmit laser driver **223** in the illustrated embodiment. The transmit post amplifier **219** may amplify the electrical signal **218A** to generate an amplified signal **218B** and provide the amplified signal **218B** to the transmit CDR **221**, which may reshape and retimed the amplified signal **218B** to generate a reshaped and retimed signal **218C**. The reshaped and retimed signal **218C** may be delivered to a transmit laser driver **223** configured to drive a fiber-side transmitter **225**. More specifically, the transmit laser driver **223** may receive the reshaped and retimed signal **218C** and drive the fiber-side transmitter **225** with a drive signal **218D** that causes the fiber-side transmitter **225** to emit an optical signal representative of the information in the reshaped and retimed signal **218C**. The fiber-side transmitter **225** acts as an electro-optic transducer by transforming the drive signal **218D** into an optical signal. The optical signal emitted by the fiber-side transmitter **225** may then be transmitted through a fiber-side optical port **227** onto a corresponding fiber link, such as one of the fiber links **112** of FIG. 1. In some embodiments, the reshaping performed by the transmit CDR **221** and the configuration of the fiber-side transmitter **225** conditions and/or configures the optical signal emitted by the fiber-side transmitter **225** for the specific conditions (e.g., link length, wavelength channel) of the fiber link onto which the optical signal may be emitted. Accordingly, the DOEC module **102** may enable an optical signal to be configured to work with any fiber length and/or at any specific wavelength parameters.

In the illustrated embodiment of FIG. 2, a first pathway including the receive post amplifier **205**, the receive CDR **207**, and the receive laser driver **209**, is depicted for processing receive data, while a second distinct pathway including

the transmit post amplifier **219**, the transmit CDR **221**, and the transmit laser driver **223**, is depicted for processing transmit data. In other embodiments, the DOEC module **102** may include a single pathway including, e.g., a post amplifier, a CDR and a laser driver for processing both transmit and receive data.

Each of the fiber-side receiver **202** and the host-side receiver **217** may include any suitable optical receiver for converting optical signals to electrical signals. For instance, each of the fiber-side receiver **202** and the host-side receiver **217** may include, but is not limited to, a PIN photodiode, an avalanche photodiode, or the like.

Each of the host side transmitter **211** and the fiber-side transmitter **225** may include any suitable optical transmitter for converting electrical signals to optical signals. For instance, each of the host-side transmitter **211** and the fiber-side transmitter **225** may include, but is not limited to, a Fabry-Perot (FP) laser, a distributed feedback (DFB) laser, a distributed Bragg reflector (DBR) laser, a vertical cavity surface emitting laser (VCSEL), or the like.

In some embodiments, the host-side transmitter **211** and the host-side receiver **217** are referred to herein as an optical host interface since the DOEC module **102** emits optical signals to and/or receives optical signals from the host card **104** via the host-side transmitter **211** and the host-side receiver **217**. In an analogous manner, the fiber-side receiver **202** and the fiber-side transmitter **225** may be referred to herein as an optical network interface since the DOEC module **102** receives optical signals from and/or emits optical signals to the network via the fiber-side receiver **202** and the fiber-side transmitter **225**. In these and other embodiments, the integrated circuit **203** is generally configured to condition electrical signals communicated between the optical host interface and the optical network interface, such as the electrical signals **204A** and **218A**, as described herein.

Although not required, the DOEC module **102** may optionally include a management interface including a control module **229**, one or more pins **233** of the DOEC module **102** and/or a memory **231**. The management interface may communicate between the host card **104** and the DOEC module **102** to monitor low-speed signals relating to the operation of the DOEC module **102** including alarms, module controls, diagnostic monitoring, and the like. The control module **229** of the management interface may include, but is not limited to a microprocessor, a microcontroller, a processor, a controller, or other suitable processing device. The control module **229** may have access to, and may communicate electronically with the memory **231**. The memory **231**, in the illustrated embodiment, may be electrically erasable and programmable read only memory (EEPROM). The memory **231** and the control module **229** may be packaged together in the same package or in different packages without restriction. The memory **231** may also be any other non-volatile memory source. The control module **229** recognizes instructions that follow a particular instruction set, and may perform normal operations such as, for example, readings of temperature levels, transmit/receive power levels, and the like. Two external lines **229A** and **229B** are possibly implemented using a two-wire interface such as I2C as shown in FIG. 2, however other interfaces may alternately or additionally be implemented. The precise structure of the instruction set is not important to the principles described herein as the instruction set may be optimized around a particular hardware environment, and as the precise hardware environment is not important to the principles described herein.

Although not required, the DOEC module **102** illustrated in FIG. 2 may optionally provide a low-speed electrical inter-

face including the one or more pins **233** as one component of the management interface. The pins **233** communicate low-speed data with the external host **100** to allow for digital diagnostic monitoring and readings of temperature levels, transmit/receive power levels, in addition to power supply.

FIG. **3** schematically illustrates an example of multiple DOEC modules **301**, **305** that may be used to drop and retransmit signals. Each of the DOEC modules **301**, **305** may correspond to the DOEC modules **102** described with respect to FIGS. **1-2**. In more detail, when the link between a host side transmitter **303** of a DOEC module **301** and a host (not shown) is experiencing a fault, a receive signal emitted by the transmitter **303** may be dropped by the host and retransmitted through the DOEC module **305**. A fault signal may be an alarm signal that indicates a fault. Specifically, a fault signal may relate to a receive signal emitted by host side transmitter **303** being unable to reach a host (not shown). Such a fault signal may be sent by the host to the module **301** possibly through a management interface to indicate the fault. A receive signal unable to reach a host (not shown) may then be redirected to a host side receiver **307** of the DOEC module **305** and then to the host through the host side transmitter **308**. An integrated circuit of the DOEC module **305**, such as the integrated circuit **203** described in FIG. **2**, may be configured to receive the signal from the host side receiver **307** and provide the signal to the host side transmitter **308**. The integrated circuit of the DOEC module **305** may reshape and retiming the signal for communication to the host. Thus, FIG. **3** illustrates how multiple DOEC modules may cooperate to perform drop and transmit functions in case of fault, and may enable transmission flexibility over multiple channels.

In some embodiments, at least one reflector **309** disposed in the signal path of the signal emitted by the host side transmitter **303** can be activated such that the signal emitted by the host side transmitter **303** may be redirected to the host side receiver **307** via reflection. The reflector **309** may allow pass through when not activated. Although the embodiment of FIG. **3** depicts a single reflector **309**, more generally any suitable number and location of reflectors can be provided for redirecting the emitted signal from the host side transmitter **303** of DOEC module **301** to the host side receiver **307** of the DOEC module **305**.

FIG. **4** is a flowchart of an example method **400** for converting a transmit optical signal. In some embodiments, the method **400** may be performed by a DOEC module, such as the DOEC module **102** described above. The method **400** may include receiving a first transmit optical signal form **401**. The first transmit optical signal form may be received **401** from a host, such as the external host **100** of FIG. **1**.

The method **400** may also include converting the first transmit optical signal form to an electrical signal **403**. The first transmit optical signal form may be converted to an electrical signal by an optical receiver, such as the host-side receiver **217** of FIG. **2**.

The method **400** may also include reshaping and retiming the electrical signal **405**. The electrical signal may be reshaped and retimed by an integrated circuit, such as the integrated circuit **203** of FIG. **2**. The step **405** of reshaping and retiming the electrical signal is optional and may be omitted in some embodiments.

The method **400** may also include converting the electrical transmit signal to a second transmit optical signal form **407**. The electrical signal may be converted to a second transmit optical signal form by an optical transmitter, such as the fiber-side transmitter **225** in FIG. **2**.

The method **400** may also include delivering the second transmit optical signal form to a fiber optic network **409**. The

second transmit optical signal form can be delivered to a fiber optic network by an optical port, such as the fiber-side optical port **227** in FIG. **2**.

FIG. **5** is a flowchart of an example method **500** for converting a receive optical signal. In some embodiments, the method **500** may be performed by a DOEC module, such as the DOEC module **102** described above in FIG. **2**. The method **500** may include receiving a first receive optical signal form **501**. The first receive optical signal may be received **501** from a link, such as one of the fiber links **112** of FIG. **1**, at the fiber-side optical port **201** in FIG. **2**.

The method **500** may also include converting the first receive optical signal form to an electrical signal **503**. The first receive optical signal form may be converted to an electrical signal by an optical receiver, such as the fiber-side receiver **202** of FIG. **2**.

The method **500** may also include reshaping and retiming the electrical signal **505**. The electrical signal may be reshaped and retimed by an integrated circuit, such as the integrated circuit **203** of FIG. **2**. The step **505** of reshaping and retiming the electrical signal is optional and may be omitted in some embodiments.

The method **500** may also include converting the electrical transmit signal to a second receive optical signal form **507**. The electrical signal may be converted to a second receive optical signal form by an optical transmitter, such as the host-side optical transmitter **211** in FIG. **2**.

The method **500** may also include delivering the second receive optical signal form to an external host **509**. The second receive optical signal form can be delivered to an external host by an optical port, such as the host-side optical port **213** in FIG. **2**.

With respect to the use of substantially any plural and/or singular terms herein, those having skill in the art can translate from the plural to the singular and/or from the singular to the plural as is appropriate to the context and/or application. The various singular/plural permutations may be expressly set forth herein for sake of clarity.

It will be understood by those within the art that, in general, terms used herein, and especially in the appended claims (e.g., bodies of the appended claims) are generally intended as “open” terms (e.g., the term “including” should be interpreted as “including but not limited to,” the term “having” should be interpreted as “having at least,” the term “includes” should be interpreted as “includes but is not limited to,” etc.). It will be further understood by those within the art that if a specific number of an introduced claim recitation is intended, such an intent will be explicitly recited in the claim, and in the absence of such recitation no such intent is present. For example, as an aid to understanding, the following appended claims may contain usage of the introductory phrases “at least one” and “one or more” to introduce claim recitations. However, the use of such phrases should not be construed to imply that the introduction of a claim recitation by the indefinite articles “a” or “an” limits any particular claim containing such introduced claim recitation to embodiments containing only one such recitation, even when the same claim includes the introductory phrases “one or more” or “at least one” and indefinite articles such as “a” or “an” (e.g., “a” and/or “an” should be interpreted to mean “at least one” or “one or more”); the same holds true for the use of definite articles used to introduce claim recitations. In addition, even if a specific number of an introduced claim recitation is explicitly recited, those skilled in the art will recognize that such recitation should be interpreted to mean at least the recited number (e.g., the bare recitation of “two recitations,” without other modifiers, means at least two recitations, or two or more

recitations). Furthermore, in those instances where a convention analogous to “at least one of A, B, and C, etc.” is used, in general such a construction is intended in the sense one having skill in the art would understand the convention (e.g., “a system having at least one of A, B, and C” would include but not be limited to systems that have A alone, B alone, C alone, A and B together, A and C together, B and C together, and/or A, B, and C together, etc.). In those instances where a convention analogous to “at least one of A, B, or C, etc.” is used, in general such a construction is intended in the sense one having skill in the art would understand the convention (e.g., “a system having at least one of A, B, or C” would include but not be limited to systems that have A alone, B alone, C alone, A and B together, A and C together, B and C together, and/or A, B, and C together, etc.). It will be further understood by those within the art that virtually any disjunctive word and/or phrase presenting two or more alternative terms, whether in the description, claims, or drawings, should be understood to contemplate the possibilities of including one of the terms, either of the terms, or both terms. For example, the phrase “A or B” will be understood to include the possibilities of “A” or “B” or “A and B.”

In addition, where features or aspects of the disclosure are described in terms of Markush groups, those skilled in the art will recognize that the disclosure is also thereby described in terms of any individual member or subgroup of members of the Markush group.

As will be understood by one skilled in the art, for any and all purposes, such as in terms of providing a written description, all ranges disclosed herein also encompass any and all possible subranges and combinations of subranges thereof. Any listed range can be easily recognized as sufficiently describing and enabling the same range being broken down into at least equal halves, thirds, quarters, fifths, tenths, etc. As a non-limiting example, each range discussed herein can be readily broken down into a lower third, middle third and upper third, etc. As will also be understood by one skilled in the art all language such as “up to,” “at least,” and the like include the number recited and refer to ranges which can be subsequently broken down into subranges as discussed above. Finally, as will be understood by one skilled in the art, a range includes each individual member. Thus, for example, a group having 1-3 cells refers to groups having 1, 2, or 3 cells. Similarly, a group having 1-5 cells refers to groups having 1, 2, 3, 4, or 5 cells, and so forth.

From the foregoing, it will be appreciated that various embodiments of the present disclosure have been described herein for purposes of illustration, and that various modifications may be made without departing from the scope and spirit of the present disclosure. Accordingly, the various embodiments disclosed herein are not intended to be limiting, with the true scope and spirit being indicated by the following claims.

All references recited herein are incorporated herein by specific reference in their entirety.

There may be other embodiments without departing from its spirit or essential characteristics. The described embodiments are to be considered in all respects only as illustrative and not restrictive. The scope of the invention is, therefore, indicated by the appended claims rather than by the foregoing description. All changes which come within the meaning and range of equivalency of the claims are to be embraced within their scope.

What is claimed is:

1. A dual optical-electrical conversion (DOEC) module comprising:

- an optical host interface comprising an optical transmitter and an optical receiver;
- an optical network interface comprising an optical transmitter and an optical receiver; and,
- an integrated circuit configured to condition electrical signals communicated between the optical host interface and the optical network interface, wherein:
 - the optical receiver of the optical host interface is selectively optically couplable to a second optical transmitter of a second optical host interface of a second DOEC module;
 - in response to a fault on a first link between a host and the second optical transmitter of the second optical host interface of the second DOEC module, the optical receiver of the optical host interface is configured to receive an optical signal from the second optical transmitter of the second optical host interface of the second DOEC module and to convert the optical signal to an electrical signal; and
 - the integrated circuit is configured to receive the electrical signal from the optical receiver of the optical host interface and to provide the electrical signal to the optical transmitter of the optical host interface for optical transmission to the host over a second link between the optical host interface and the host.

2. The DOEC module of claim 1, wherein the optical receiver of the host interface and the optical transmitter of the network interface are configured to cooperate to transform a transmit optical signal received from the host from a first transmit optical signal form to a second transmit optical signal form.

3. The DOEC module of claim 1 wherein the optical receiver of the network interface and the optical transmitter of the host interface are configured to cooperate to transform a receive optical signal received from an optical network from a first receive optical signal form to a second receive optical signal form.

4. The DOEC module of claim 1, wherein the optical host interface and the optical network interface are configured to cooperate with differing parameters, comprising at least one of:

- multiple different wavelengths; or
- multiple different fiber link lengths.

5. The DOEC module of claim 1, wherein the integrated circuit comprises at least one of:

- a post amplifier;
- a laser driver; and,
- a clock and data recovery circuit.

6. The DOEC module of claim 1, further comprising a management interface, the management interface comprising:

- a plurality of pins of the DOEC module;
- a control module; and
- a memory.

7. The DOEC module of claim 6, wherein the memory comprises electrically erasable programmable read-only memory (EEPROM).

8. The DOEC module of claim 6, wherein the DOEC module and the second DOEC module are configured to cooperate to allow a data carrying signal to drop and transmit from the DOEC module to the second DOEC module.

9. The DOEC module of claim 6, wherein the plurality of pins is configured to provide an electrical interface between the host and the DOEC module for at least one of communi-

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cating alarms, controls, digital diagnostic monitoring, two-wire communication, rate select and power supply.

10. The DOEC module of claim **9**, wherein the alarms comprise at least one of:

- a fault signal from the optical transmitter of the optical host interface;
- a fault signal from the optical transmitter of the optical network interface;
- a loss of signal from the optical receiver of the optical host interface; and
- a loss of signal from the optical receiver of the optical network interface.

11. A method for transforming an optical signal, the method comprising:

- receiving a first optical signal in a first optical signal form;
- converting the first optical signal to an electrical signal;
- reshaping and retiming the electrical signal;
- converting the reshaped and retimed electrical signal into a second optical signal in a second optical signal form;
- transmitting the second optical signal through a selectively activated reflector positioned in a signal path of the second optical signal to an electro-optical conversion chip (e/o chip) coupled to an Application Specific Integrated Circuit or Physical layer (ASIC/PHY) chip of an external host;
- in response to detecting a loss of signal fault of the second optical signal, activating the reflector to redirect the second optical signal from a first DOEC module that generated the second optical signal to a different second DOEC module;
- generating a third optical signal representing the second optical signal at the second DOEC module; and
- transmitting the third optical data signal from the second DOEC module to the e/o chip of the external host.

12. The method of claim **11**, wherein a wavelength of the second optical signal in the second optical signal form is different than a wavelength of the first optical signal in the first optical signal form.

13. The method of claim **11**, wherein:

- receiving the first optical signal in the first optical signal form includes receiving the first optical signal from the e/o chip coupled to the ASIC/PHY chip of the external host, the first optical signal being received over a first fiber link from the e/o chip having a first link length; and
- the second optical signal in the second optical signal form is suitable for a second link length of a second link to a network, the second link length being different than the first link length.

14. The method of claim **13**, wherein the second optical signal in the second optical signal form has a different wavelength than the first optical signal in the first optical signal form.

15. The method of claim **11**, wherein:

- receiving the first optical signal in the first optical signal form includes receiving the first optical signal from a network over a first fiber link having a first link length; and
- the second optical signal in the second optical signal form is suitable for a second link length of a second link to the e/o chip coupled to the ASIC/PHY chip of the external host, the second link length being different than the first link length.

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16. The method of claim **15**, wherein the second optical signal in the second optical signal form has a different wavelength than the first optical signal in the first optical signal form.

17. A system for transforming optical data signals to be adaptable to differing parameters between a host and a network, the system comprising:

- a host application specific integrated circuit or physical layer (ASIC/PHY) chip;
- an electro-optical conversion chip (e/o chip) coupled to the ASIC/PHY chip;

- a plurality of optical ports optically coupled to the e/o chip;
- a plurality of DOEC modules, each optically coupled to a corresponding one of the plurality of optical ports on a host side and to a network on a network side of the corresponding module; and

- a selectively activated reflector positioned in a first optical link between the e/o chip and a first DOEC module included in the plurality of DOEC modules, wherein:

the e/o chip is configured to convert electrical data signals from the ASIC/PHY chip to optical data signals in a first form emitted to the plurality of DOEC modules coupled to the plurality of ports;

each of the plurality of DOEC modules is configured to convert optical data signals in the first form received from the e/o chip to optical data signals in a second form emitted onto the network;

each of the plurality of DOEC modules is further configured to convert optical data signals in a third form received from the network to optical data signals in a fourth form emitted to the e/o chip; and

the e/o chip is further configured to convert optical data signals in the fourth form received from the plurality of DOEC modules to electrical data signals emitted to the ASIC/PHY chip;

the first DOEC module is configured to emit a first optical data signal in the fourth form that is transmitted through the selectively activated reflector to the e/o chip in an absence of detection of a loss of signal fault of the first optical data signal;

in response to detection of a loss of signal fault of the first optical data signal, the selectively activated reflector is configured to redirect the first optical data signal to a second DOEC module included in the plurality of DOEC modules;

in response to receipt of the first optical data signal from the first DOEC module, the second DOEC module is configured to generate a second optical data signal that represents the first optical data signal; and

the second DOEC module is configured to transmit the second optical data signal to the e/o chip over a second optical link between the e/o chip and the second DOEC module.

18. The system of claim **17**, wherein each of the plurality of DOEC modules comprises:

- an optical host interface comprising an optical transmitter and an optical receiver;
- an optical network interface comprising an optical transmitter and an optical receiver; and,
- an integrated circuit configured to condition electrical signals communicated between the optical host interface and the optical network interface.

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